# Hon Hai Technology Group Announces Strategic Collaboration with Intel to Advance Next-Generation AI Rack, Edge AI, and Physical AI Platforms

New Taipei City, Taiwan, June 4, 2026 — Hon Hai Technology Group (“Foxconn”) (TWSE:2317) today announced a strategic collaboration with Intel (NASDAQ: INTC) to jointly accelerate the development and deployment of next-generation AI infrastructure and intelligent computing platforms.

By combining Intel’s strengths in processor architecture, silicon technologies, and software ecosystem with Foxconn’s global manufacturing scale, system integration expertise, and AI data center deployment capabilities, the two companies will explore comprehensive AI solutions spanning silicon, rack, system, and application layers. The collaboration also aims to accelerate the large-scale deployment of AI-driven technologies across edge and physical AI applications.

Young Liu, Chairman and CEO of Hon Hai Technology Group, said:

“AI is rapidly transforming industries and society worldwide. Through our ‘3+3+3’ strategy, Foxconn continues to advance key technologies including AI, semiconductors, and next-generation communications, while driving the development of our three core platforms: smart manufacturing, smart EV, and smart city. Our collaboration with Intel will combine the strengths of both companies across computing platforms, system integration, and global supply chain capabilities to jointly build next-generation AI infrastructure, Edge AI, and Physical AI ecosystems, accelerating the adoption of AI applications worldwide.”

Lip-Bu Tan, Intel CEO, said

“The rapid growth of AI—especially in inference and agentic workloads at scale—is redefining what modern computing must deliver. These demands require innovation across the full stack—from new silicon and chip design to rackscale systems and extending all the way to edge and physical AI deployments. Our collaboration with Foxconn brings together two innovation leaders with deep expertise in chip design, rack-scale solutions, and global systems integration. Together, we are accelerating the delivery of end-to-end platforms that unlock new capabilities and extend the impact of AI worldwide.”

Under the collaboration framework, Intel and Foxconn will work together to scale AI-driven solutions by leveraging Intel’s computing platforms, silicon technologies, and software ecosystem together with Foxconn’s system integration capabilities, manufacturing expertise, and global customer reach.

In the AI Rack domain, the two companies will explore the development and commercialization of rack-scale AI infrastructure solutions, including Intel Xeon-based CPU racks and AI accelerator architectures. The collaboration will also focus on advancing high-speed interconnect technologies, thermal and liquid cooling designs, system telemetry, and AI data center scalability to deliver high-performance, energy-efficient AI deployment solutions.

In the Edge and Physical AI domain, Intel and Foxconn will jointly define next-generation Edge AI and Physical AI platform architectures, targeting emerging applications such as agentic AI, edge intelligence, and robotics. The collaboration will further promote and support diverse applications across smart manufacturing, smart cities, automotive, and robotics.

In addition, the two companies will explore opportunities in design services, including custom ASICs, SoCs, and system integration solutions. By combining Intel’s end-to-end silicon capabilities with Foxconn’s comprehensive design and manufacturing ecosystem, the collaboration spans silicon, modules, and systems to address global market opportunities.